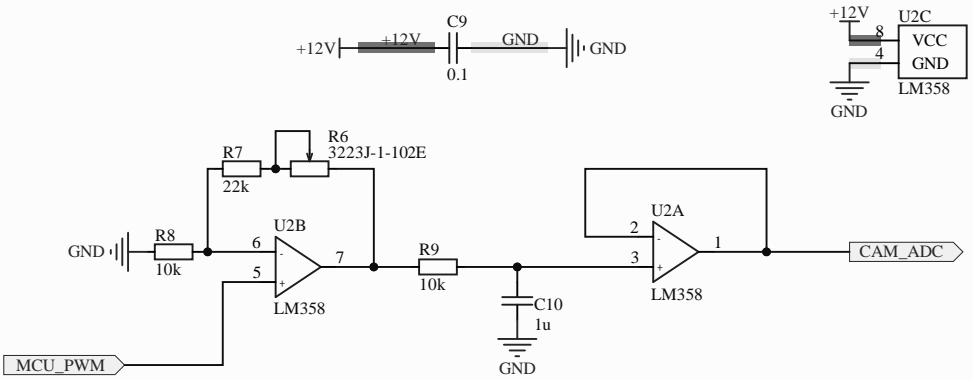
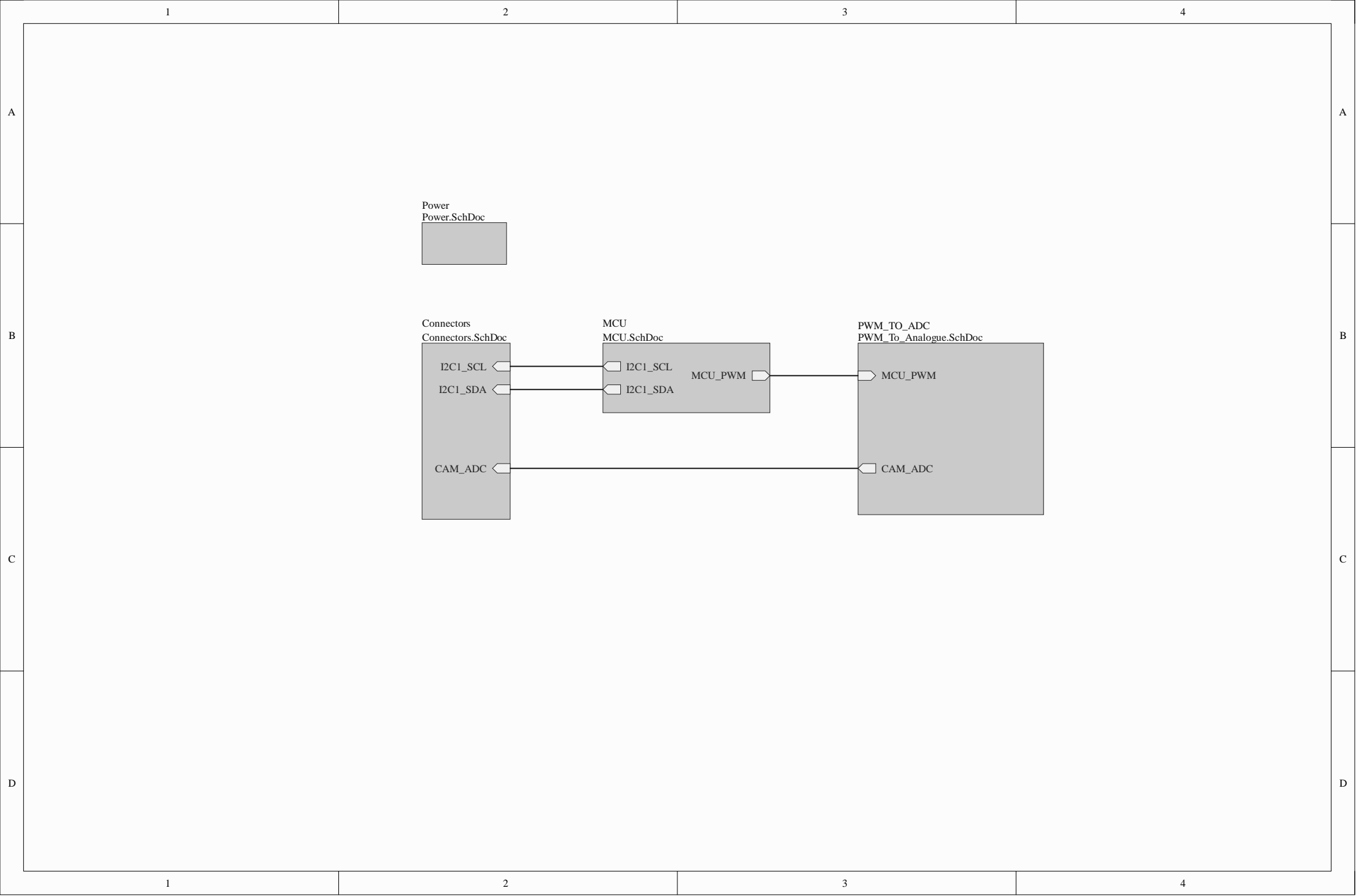
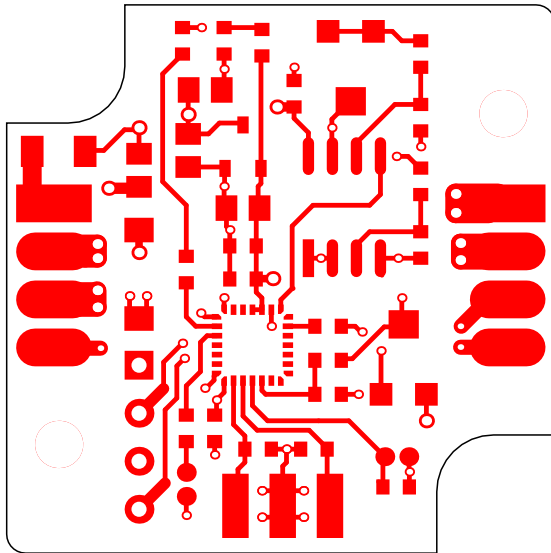


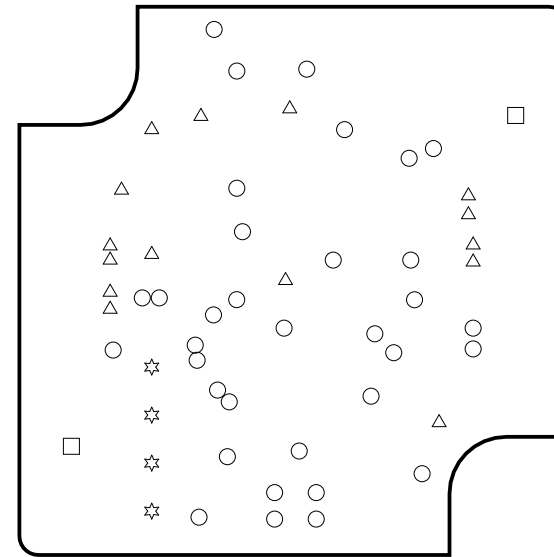
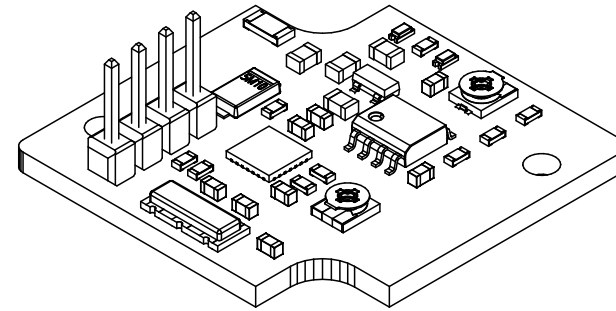
MCP1703AT-3302E/CB



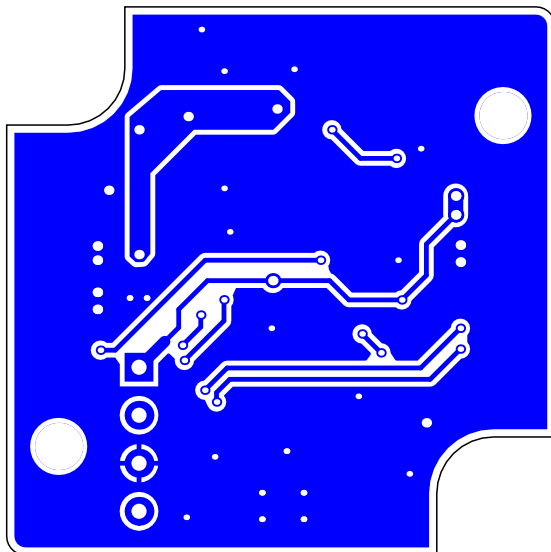




Top Layer (Scale 5:2)



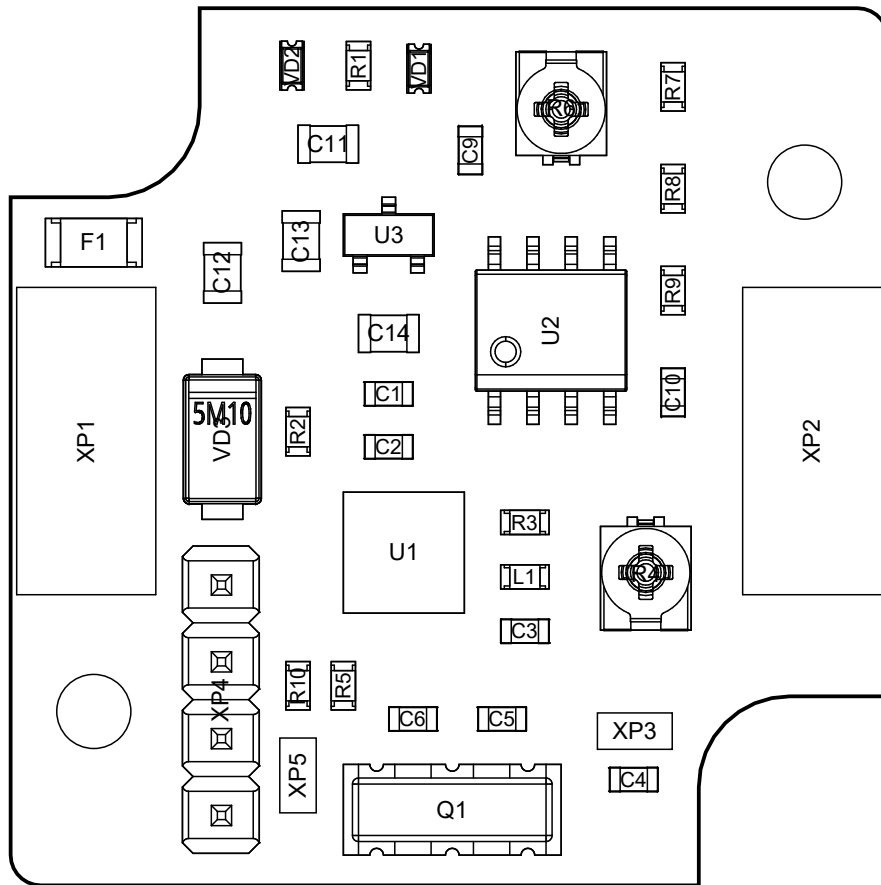
Drill Drawing View (Scale 5:2)



Bottom Layer (Scale 5:2)

Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
○	34	0.30mm	Plated	
△	15	0.50mm	Plated	
☆	4	0.80mm	Plated	
□	2	2.50mm	Non-Plated	
55 Total				



View from Top side (Scale 4:1)

Bill Of Materials

Line #	Designator	Comment	Quantity	Footprint
1	C1, C2, C3, C4, C9, C12, C13, C14	0.1	8	CAP_0603, CAP_0805
2	C5, C6	22p	2	CAP_0603
3	C10	1u	1	CAP_0603
4	C11	0.33	1	CAP_0805
5	F1	500mA	1	SMD_1206
6	L1		1	SMD_0603
7	Q1	8MHz	1	CSTCC-CRYSTAL
8	R1, R5	100k	2	SMD_0603
9	R2	1k	1	SMD_0603
10	R3, R10	330	2	SMD_0603
11	R4		1	RES-ADJ-SMD-Panasonic
12	R6	3223J-1-102E	1	RES-ADJ-SMD-Panasonic
13	R7	22k	1	SMD_0603
14	R8, R9	10k	2	SMD_0603
15	U1	STM32F042G6U6	1	UFQFPN_4x4_STM32F042G6U6
16	U2	LM358	1	SO8-150mil
17	U3	MCP1703AT-3302E/CB	1	SOT23-3
18	VD1	RED	1	LED_0603
19	VD2	GREEN	1	LED_0603
20	VD3	SMA6F12A	1	DO-221AC
21	XP1	CAM	1	HEAD-SMD-2.54/4
22	XP2	TEMP_SR	1	HEAD-SMD-2.54/4
23	XP3	RST	1	HEAD_MICRO_SF_1.27-2
24	XP4	CON_4	1	HEAD-1/4/2.54
25	XP5	CON_2	1	HEAD_MICRO_SF_1.27-2

Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.01mm	Solder Resist	Solder Mask	GTS
Copper	Top Layer	0.04mm		Signal	GTL
		1.60mm	FR-4	Dielectric	
Copper	Bottom Layer	0.04mm		Signal	GBL
Surface Material	Bottom Solder	0.01mm	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
Total thickness: 1.69mm					

A

B

C

D

E

1

1

2

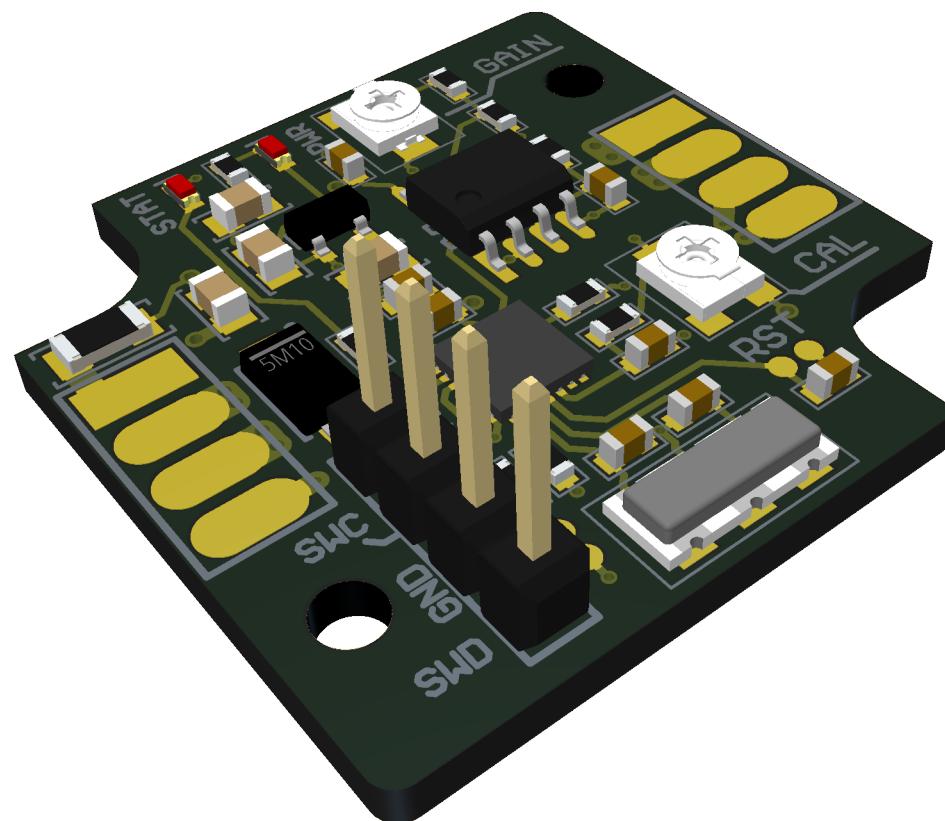
2

3

3

4

4



A

B

C

D

E